

# C0603C473K1RECTU

Aliases (C0603C473K1REC7867)

ESD SMD Comm X7R, Ceramic, 0.047 uF, 10%, 100 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 0603, 0.5 mm



General Information			
Series	ESD SMD Comm X7R		
Style	SMD Chip		
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II		
Features	Temperature Stable, Class II		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	4.8 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm
Packaging Specifications	

Specifications		
Capacitance	0.047 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	10%	
Voltage DC	100 VDC	
ESD Level per AEC-Q200	25,000 V ESD Level	
Dielectric Withstanding Voltage	250 VDC	
Temperature Range	-55/+125°C	
Temp. Coefficient	X7R	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms	
Dissipation Factor	2.5% 1 kHz 1.0 Vrms	
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	10 GOhms	

В	0.35mm +/-0.15mm	Dielectric Withstanding Voltage	250 VDC
		Temperature Range	-55/+125°C
Packaging Specifications		Temp. Coefficient	X7R
Packaging	T&R, 180mm, Paper Tape	Capacitance Change with	15%, 1kHz 1.0Vrms
Packaging Quantity	4000	Reference to +25°C and 0 VDC Applied (TCC)	
		Dissipation Factor	2.5% 1 kHz 1.0 Vrms
		Aging Rate	3% Loss/Decade Hour: Referee

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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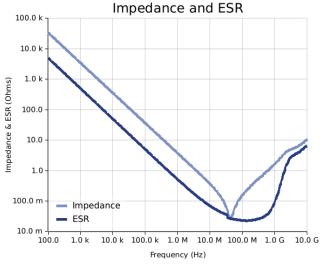
# C0603C473K1RECTU

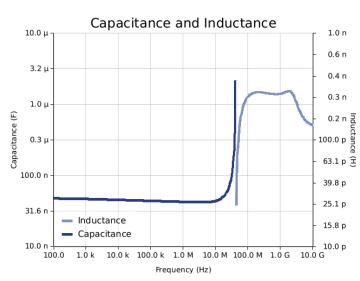
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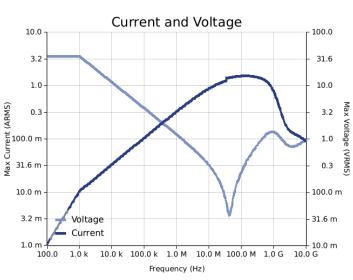
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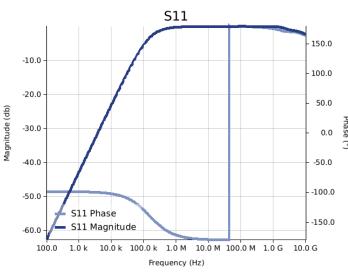
### **Simulations**

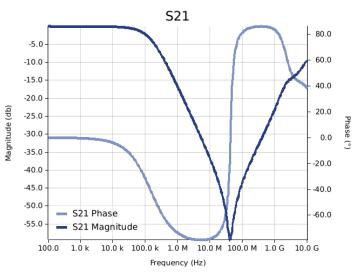
For the complete simulation environment please visit K-SIM.

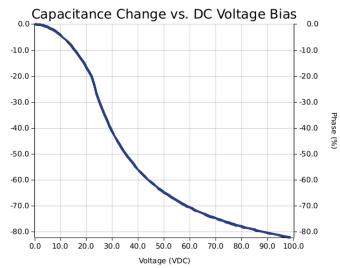












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Phase (%)



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#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

  Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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